FAIRCHILD SEMICONDUCTOR™

April 1988
Revised August 2000

74F32
Quad 2-Input OR Gate

General Description

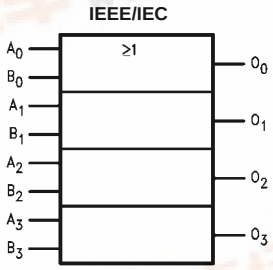
This device contains four independent gates, each of which performs the logic OR function.

Ordering Code:

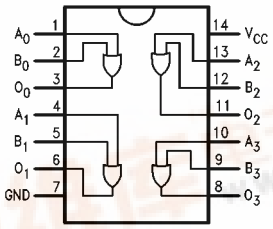
Order Number	Package Number	Package Description
74F32SC	M14A	14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-120, 0.150 Narrow
74F32SJ	M14D	14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74F32MTC	MTC14	14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
74F32PC	N14A	14-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

Logic Symbol



Connection Diagram



Unit Loading/Fan Out

Pin Names	Description	U.L. HIGH/LOW	Input I_{IH}/I_{IL} Output I_{OH}/I_{OL}
A_n, B_n	Inputs	1.0/1.0	20 µA/–0.6 mA
O_n	Outputs	50/33.3	–1 mA/20 mA

Absolute Maximum Ratings(Note 1)

Storage Temperature	−65°C to +150°C
Ambient Temperature under Bias	−55°C to +125°C
Junction Temperature under Bias	−55°C to +150°C
V_{CC} Pin Potential to Ground Pin	−0.5V to +7.0V
Input Voltage (Note 2)	−0.5V to +7.0V
Input Current (Note 2)	−30 mA to +5.0 mA
Voltage Applied to Output	
in HIGH State (with V_{CC} = 0V)	
Standard Output	−0.5V to V_{CC}
3-STATE Output	−0.5V to +5.5V
Current Applied to Output	
in LOW State (Max)	twice the rated I_{OL} (mA)
ESD Last Passing Voltage (Min)	4000V

Recommended Operating Conditions

Free Air Ambient Temperature	0°C to +70°C
Supply Voltage	+4.5V to +5.5V

Note 1: Absolute maximum ratings are values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

Note 2: Either voltage limit or current limit is sufficient to protect inputs.

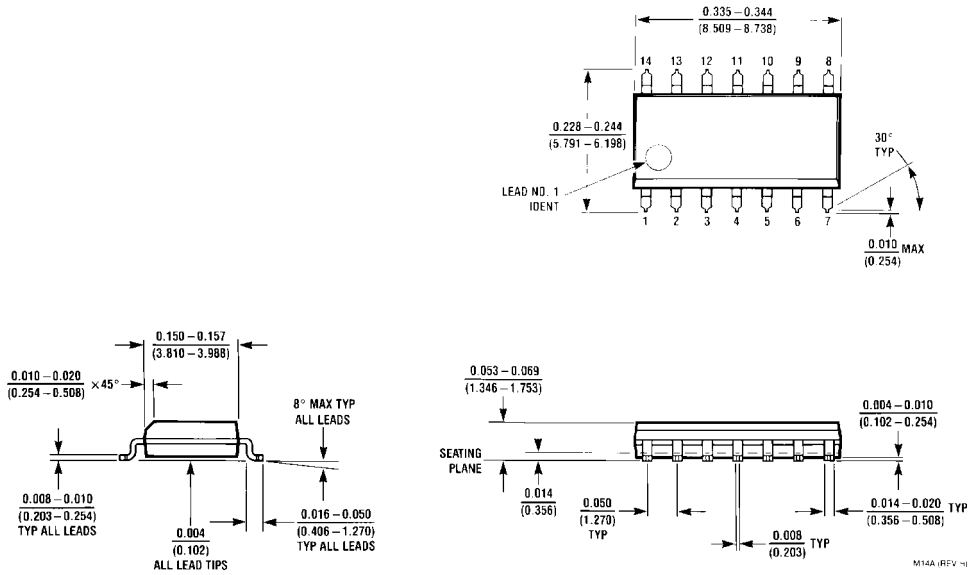
DC Electrical Characteristics

Symbol	Parameter		Min	Typ	Max	Units	V_{CC}	Conditions
V_{IH}	Input HIGH Voltage		2.0			V		Recognized as a HIGH Signal
V_{IL}	Input LOW Voltage				0.8	V		Recognized as a LOW Signal
V_{CD}	Input Clamp Diode Voltage				−1.2	V	Min	I_{IN} = −18 mA
V_{OH}	Output HIGH	10% V_{CC}	2.5			V	Min	I_{OH} = −1 mA
	Voltage	5% V_{CC}	2.7					I_{OH} = −1 mA
V_{OL}	Output LOW	10% V_{CC}			0.5	V	Min	I_{OL} = 20 mA
	Voltage							
I_{IH}	Input HIGH				5.0	µA	Max	V_{IN} = 2.7V
	Current							
I_{BVI}	Input HIGH Current				7.0	µA	Max	V_{IN} = 7.0V
	Breakdown Test							
I_{CEX}	Output HIGH				50	µA	Max	V_{OUT} = V_{CC}
	Leakage Current							
V_{ID}	Input Leakage		4.75			V	0.0	I_{ID} = 1.9 µA
	Test							All Other Pins Grounded
I_{OD}	Output Leakage				3.75	µA	0.0	V_{IOD} = 150 mV
	Circuit Current							All Other Pins Grounded
I_{IL}	Input LOW Current				−0.6	mA	Max	V_{IN} = 0.5V
I_{OS}	Output Short-Circuit Current		−60		−150	mA	Max	V_{OUT} = 0V
I_{CCH}	Power Supply Current			6.1	9.2	mA	Max	V_O = HIGH
I_{CCL}	Power Supply Current			10.3	15.5	mA	Max	V_O = LOW

AC Electrical Characteristics

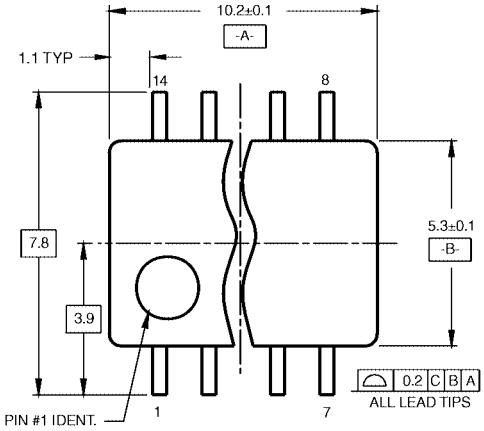
Symbol	Parameter	T_A = +25°C, V_{CC} = +5.0V, C_L = 50 pF			T_A = −55°C to +125°C, V_{CC} = +5.0V, C_L = 50 pF		T_A = 0°C to +70°C, V_{CC} = +5.0V, C_L = 50 pF		Units
		Min	Typ	Max	Min	Max	Min	Max	
t_{PLH}	Propagation Delay	3.0	4.2	5.6	3.0	7.5	3.0	6.6	ns
t_{PHL}	A_n, B_n to O_n	3.0	4.0	5.3	2.5	7.5	3.0	6.3	

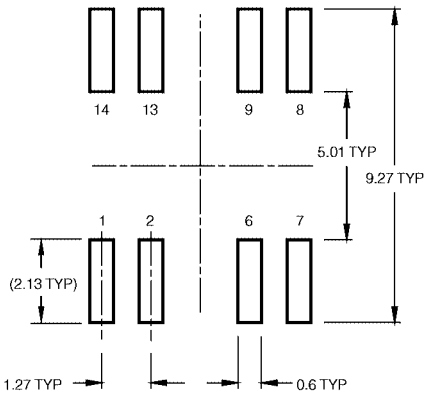
Physical Dimensions inches (millimeters) unless otherwise noted



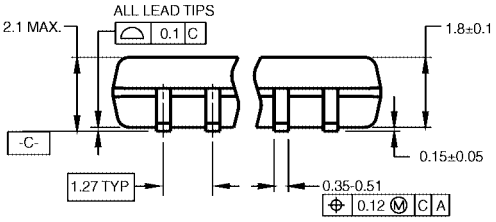
14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-120, 0.150 Narrow
Package Number M14A

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)

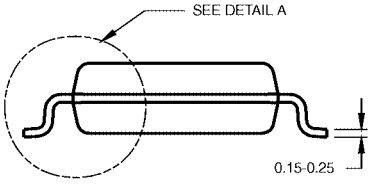


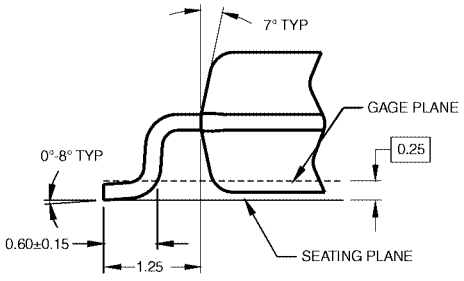


LAND PATTERN RECOMMENDATION



DIMENSIONS ARE IN MILLIMETERS





DETAIL A

NOTES:

A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.

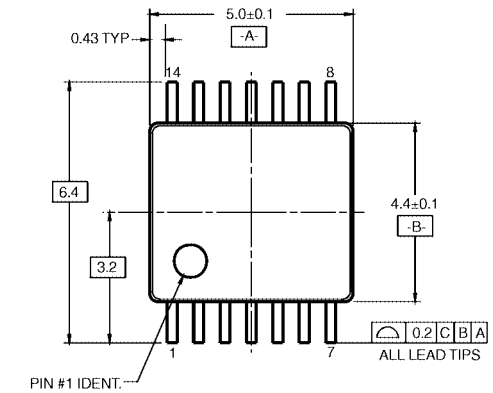
B. DIMENSIONS ARE IN MILLIMETERS.

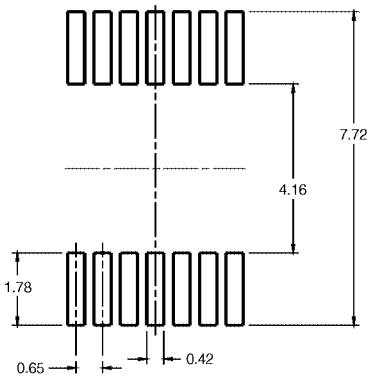
C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

M14DRevB1

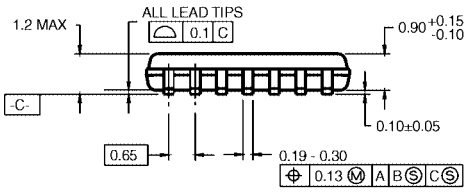
14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
Package Number M14D

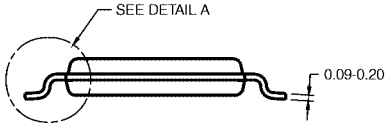
Physical Dimensions inches (millimeters) unless otherwise noted (Continued)

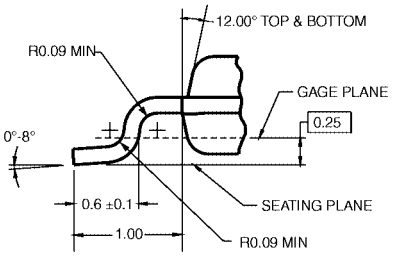




LAND PATTERN RECOMMENDATION







DETAIL A

NOTES:

A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AB, REF NOTE 6, DATE 7/93.

B. DIMENSIONS ARE IN MILLIMETERS.

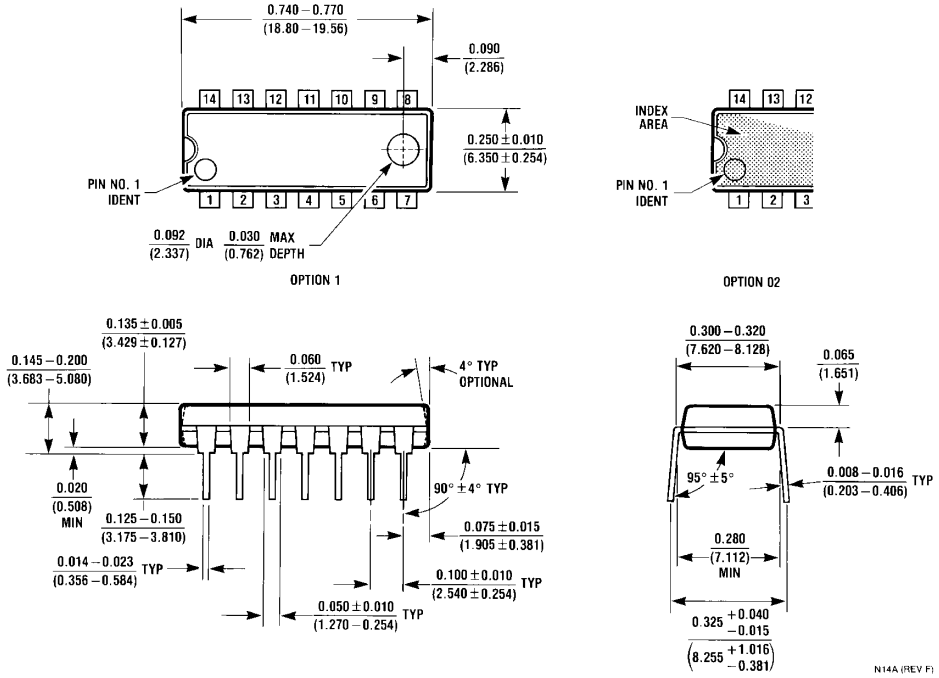
C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.

MTC14RevC3

14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
Package Number MTC14

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



14-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide
Package Number N14A